

ABSTRACT

Provided is a resin mold for imprinting which is free from transfer defects, has excellent releasability from a resin subjected to imprinting, and does not cause any defect by imprinting. The resin mold for imprinting of the present invention comprises a resin layer having a recessed and projected pattern surface, an inorganic material layer formed with a uniform thickness on at least the recessed and projected pattern surface of the resin layer, and a release agent layer formed with a uniform thickness on at least the recessed and projected pattern surface of the inorganic material layer.